

# RP902K Series Reliability Test Report

30P902K0-Ver.A

FUNCTION : Compound power supply IC with VD  
 PACKAGE : QFN0404-20 Lead free

No.	TEST ITEM	TEST CONDITION	(*)PRE-CONDITION	TIME	r/n
1	High Temp. Operating Life	Ta=125°C VDD=Vopt max. Static	Non	1000h	0/32
2	Temp. Humidity Bias	Ta=85°C RH=85% VDD=Vopt max. Static	(1)+(2)	1000h	0/22
3	High Temp. Storage	Ta=150°C	Non	1000h	0/22
4	Low Temp. Storage	Ta=-65°C	Non	1000h	0/22
5	Temp. Humidity	Ta=85°C RH=85%	(1)+(2)	1000h	0/22
6	Temp. Cycle	Ta=-65 to 150°C (30-5-30min)	(1)+(2)	100cycles	0/11
7	Thermal Shock	Ta=-65 to 150°C (5min-10s-5min)	(1)+(2)	100cycles	0/11
8	USPCBT	Ta=125°C RH=85% 2X10 <sup>5</sup> Pa VDD=Vopt max. Static	(1)+(2)	100h	0/11
9	USPCT	Ta=125°C RH=85% 2X10 <sup>5</sup> Pa	(1)+(2)	100h	0/11
10	Resistance To Soldering Heat(1)	IR Reflow (See Fig.1)	(1)	3times	0/88
11	Resistance To Soldering Heat(2)	Ta=350°C (only terminal)	(1)	5s	0/11
12	Solderability by Solder Dip Method(1)	Ta=235°C (Solder: Sn-37Pb)	(3)	5s	0/11
13	Solderability by Solder Dip Method(2)	Ta=245°C (Solder: Sn-3.0Ag-0.5Cu)	(3)	5s	0/11
14	ESD (1)	C=200pF R=0 ohm ±200V	Non	5times	0/11
15	ESD (2)	C=100pF R=1.5k ohm ±2.0kV	Non	3times	0/11
16	Latch-up	Pulse Current Injecting Method ±100mA	Non	Once	0/11

Criteria : The electrical characteristics prescribed in the individual specifications shall be satisfied.

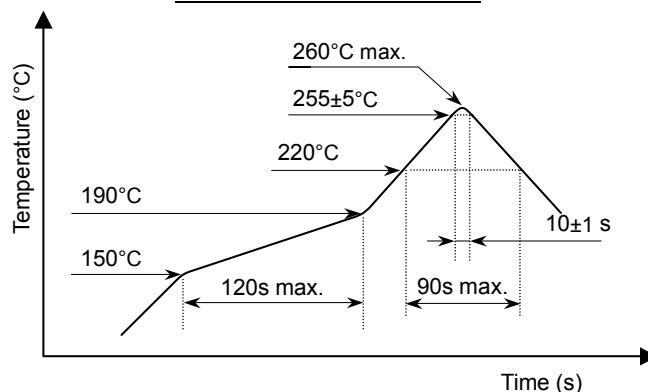
**\*)Pre-Condition**

The test shall be performed this pre-condition before testing.

- (1) Ta=30°C, RH=60%, storage 192h
- (2) IR Reflow soldering heat stress (3times)
- (3) In steam, storage=4h

[Moisture Sensitivity Level]  
 MSL Level = 3 (J-STD-020)

**HEATING TREATMENT CONDITION  
 OF INFRARED-RAY REFLOW**



Conclusion :The reliability result was good.